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Foreward

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FOREWORD

By now, the Workshop on Signal Propagation on Interconnects (SPI) has established itself as a traditional mid-May gathering in Europe for experts in the field of signal integrity, interconnect modeling, simulation and measurement on chips, boards, and packages. The aim of this Workshop is to be a forum of exchange on the latest research results in this very important technology area. The event is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation. A distinctive organization element of this Workshop is its residential nature, in order to maximize the interactions among the attendees. The SPI Workshop was initiated in Germany by Professor Joachim Mucha of Hannover University in 1997. The first four editions were held in Germany, then the Workshop moved to Italy, in 2001.

The participants to the current edition (SPI 2002) have the opportunity to listen to thirty one presentations, organized in eight sessions. The opening presentation of each day gives an overview of relevant topics: G. Katopis reports on third generation signal integrity tools, M. Swaminathan on System-On-a-Package Technologies, and E. Chiprout on the modeling of parasitics at the chip scale. There is also the possibility to meet the authors of thirteen posters, that remain displayed for the entire duration of the Workshop. The program is completed by two tutorial lectures that discuss, during an entire afternoon, recent advances in interconnect modeling and trends in optical interconnects. The serene atmosphere of the residential hotel should favor many fruitful discussions and exchanges between the over 60 participants from thirteen nations of three continents. A grant of the European Commission, for the first time this year, supports the participation of students and researchers from less favored countries.

In conclusion, we would like to thank the invited speakers, authors and tutorial instructors for their willingness to share their knowledge and experience. In fact, without their contributions, this Workshop would not have taken place. We gratefully acknowledge the sponsorship of Test Technology Technical Council of the Computer Society, and of Technical Committee on Electrical Design, Modeling and Simulation (TC-12) of the Components, Packaging and Manufacturing Technology Society. A special thank to Prof. Paul Wesling, Publication Vice President of CPMT Society. As a result of his support and help, this book of Proceedings, for the first time in the history of SPI Workshop, is an official IEEE publication and its content is visible through the IEEE online library system. Many other persons deserve a special recognition: we wish to cite the Standing Committee of SPI for their enthusiastic support to the Workshop, the Technical Program Committee for their help in reviewing papers, and the members of the local organization team for the invaluable voluntary work they dedicated to the logistics of this Workshop.

Flavio Canavero,
SPI 2002 Program Chair

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Program Co-Chair